Statement of Materials, Construction

LEAD-FREE -- 64L LQFP -- TABLE OF MATERIAL DECLARATION

No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy (with silver plating)	0.12843	Cu	7440-50-8	0.12329	34.84	96.00
				Mg	7439-95-4	0.00019	0.05	0.15
				Ni	7440-02-0	0.00385	1.09	3.00
				Si	7440-21-3	0.00083	0.24	0.65
				Silver Plating	7440-22-4	0.00026	0.07	0.20
2	Die	Silicon Chip	0.00414	Si	7440-21-3	0.00414	1.17	99.99
3	Die Attach Material	Conductive Epoxy	0.00059	Silver (Ag)	7440-22-4	0.00046	0.13	78.50
				Epoxy Resin	9003-36-5	0.00006	0.02	11.00
				Diluent	26647-14-3	0.00004	0.01	6.00
				Dicyadiamide	461-58-5	0.00001	0.00	1.00
				Hardener	620-92-8	0.00002	0.01	3.50
4	Wire	Gold	0.00107	Au	7440-57-5	0.00107	0.30	99.99
5	Lead Finish	Tin	0.00470	Sn	7440-31-5	0.00470	1.33	100
6	Encapsulation	Epoxy Resin	0.21493	Fused Silica	60676-86-0	0.17517	49.50	81.50
				Epoxy Resin	Proprietary	0.02149	6.07	10.00
				Phenol Resin	Proprietary	0.01719	4.86	8.00
				Carbon Black	1333-86-4	0.00107	0.30	0.50
Total Package Weight =			0.35385					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%